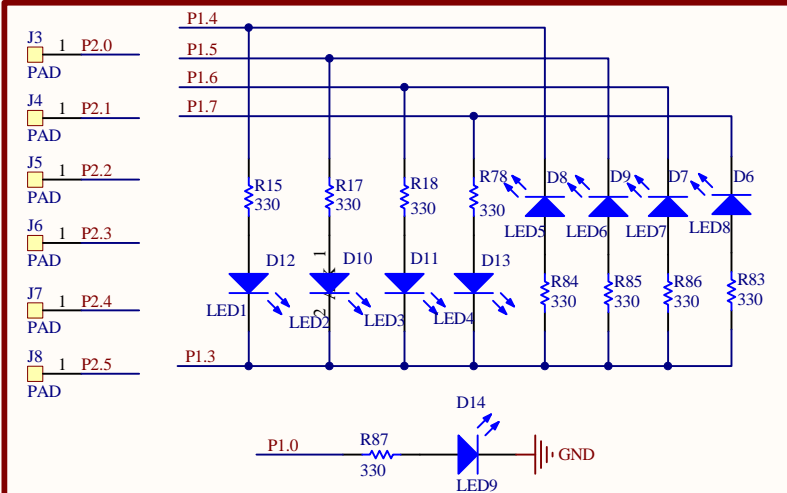
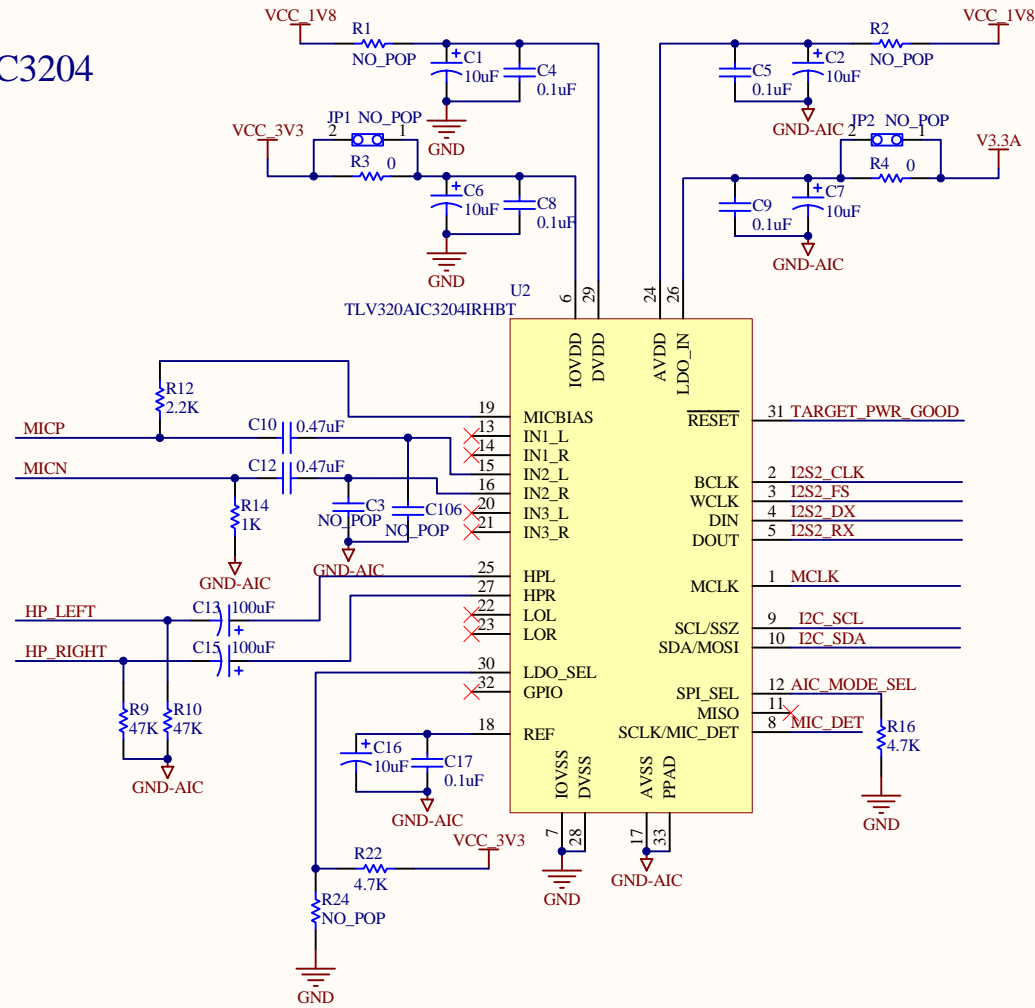
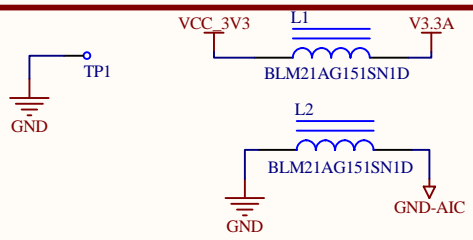
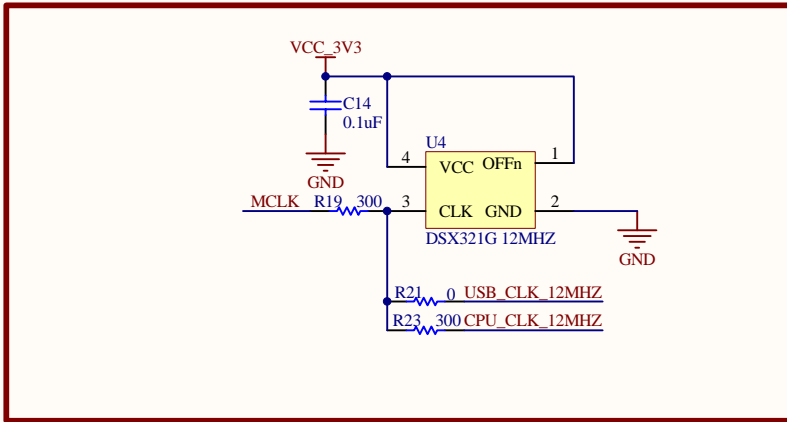
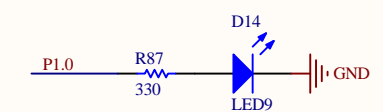


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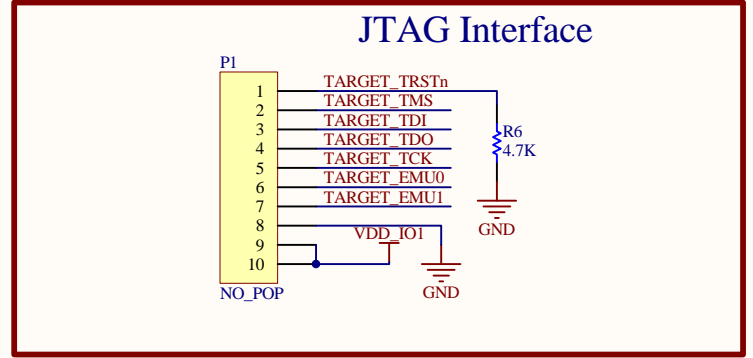
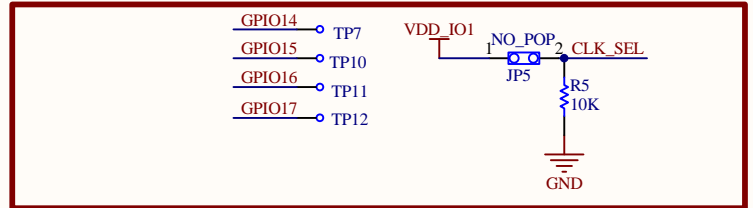
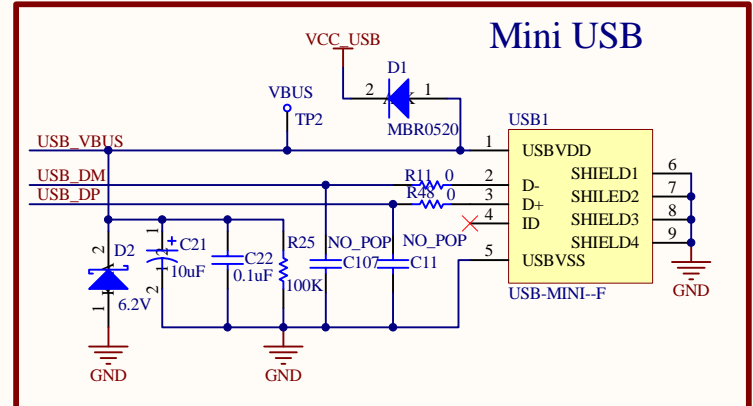
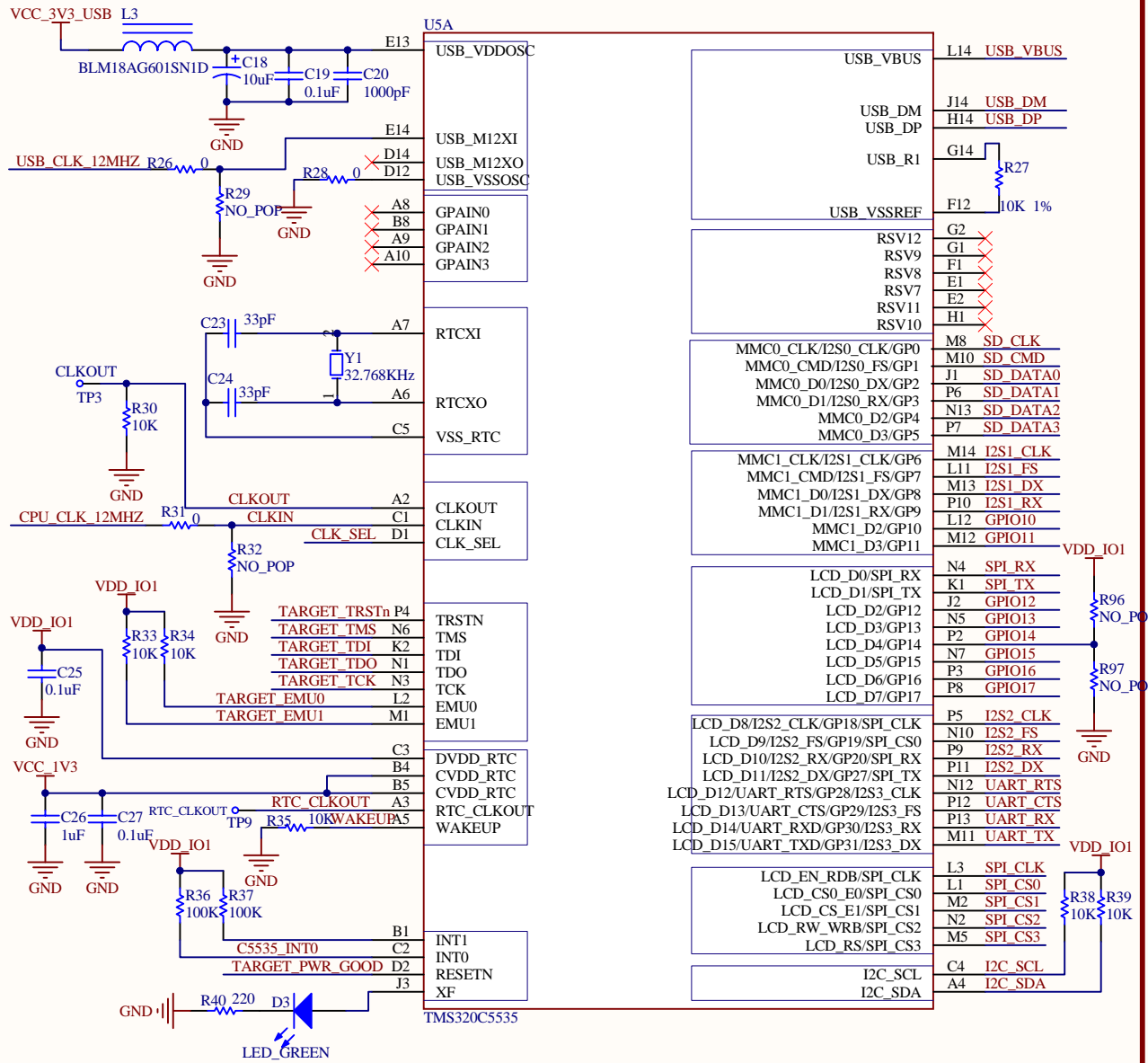
CAP TOUCH



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Document No.: 11240		Version: V2.00	
Drawn by:		Size: A4	
approved by:		approved on: 2011-12-29	
Date: 2011-12-26		Sheet 1 of 6	
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1		revised by:	Date:
2		revised by:	Date:
3		revised by:	Date:



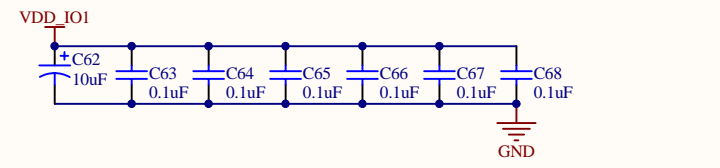
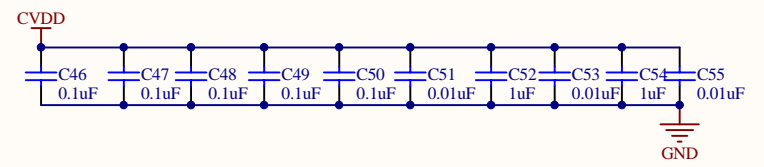
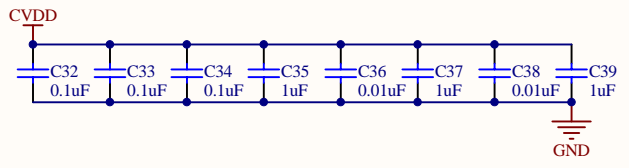
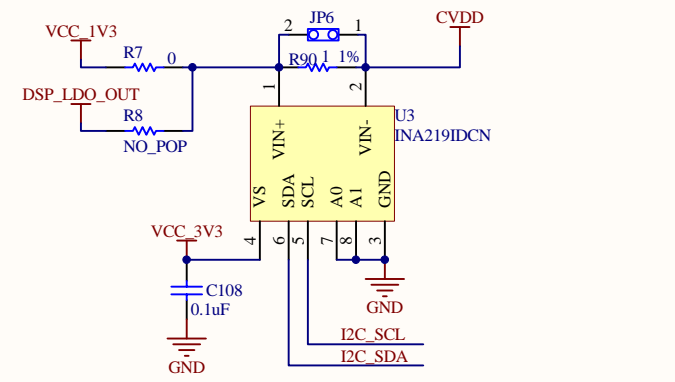
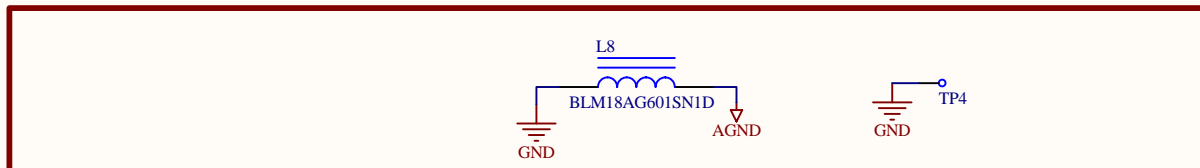
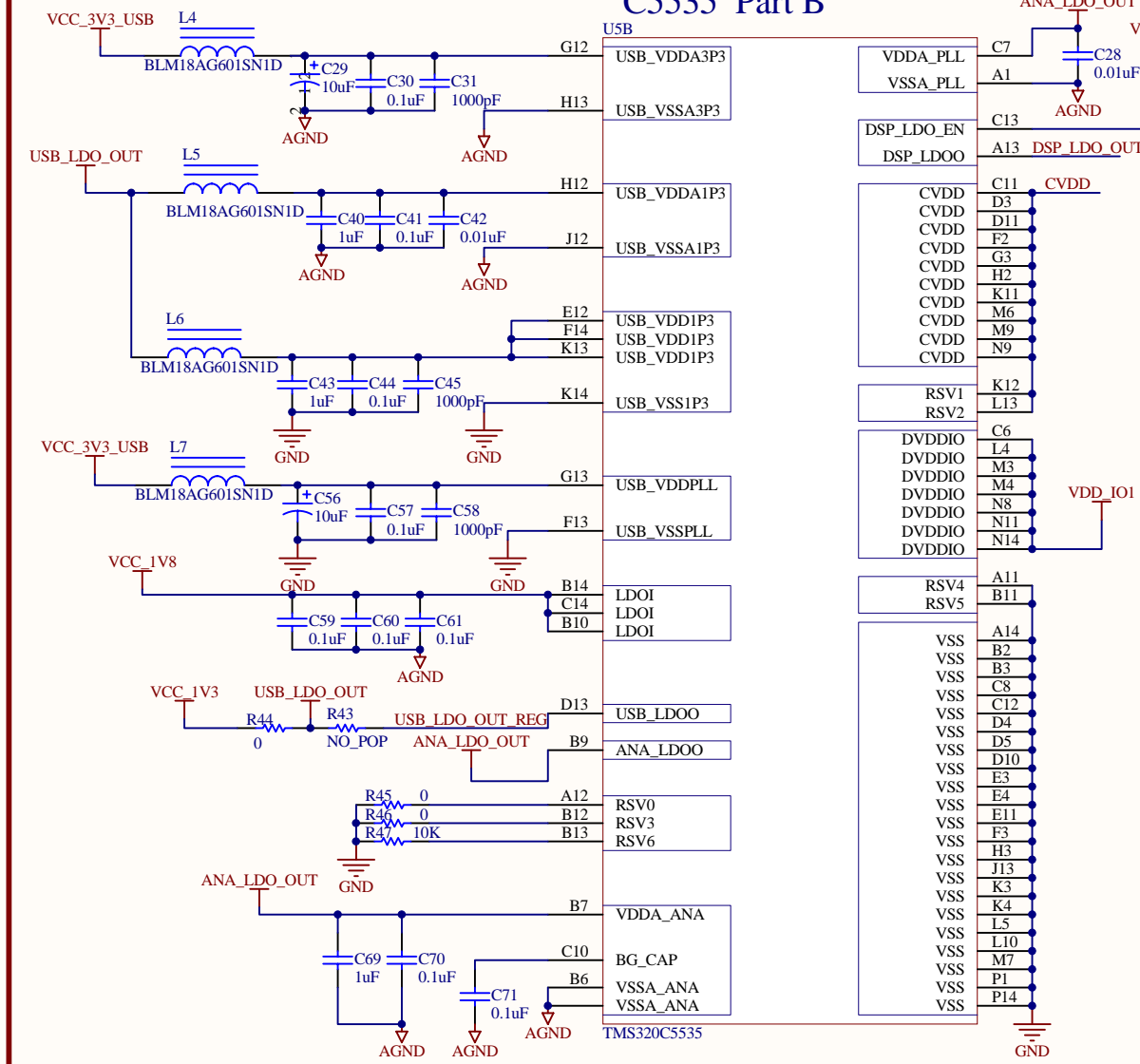
C5535 Part A



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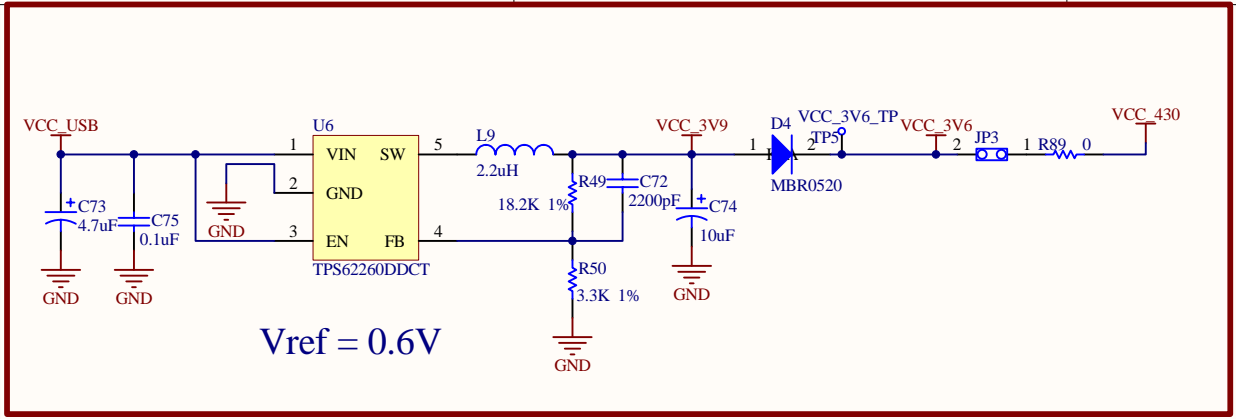


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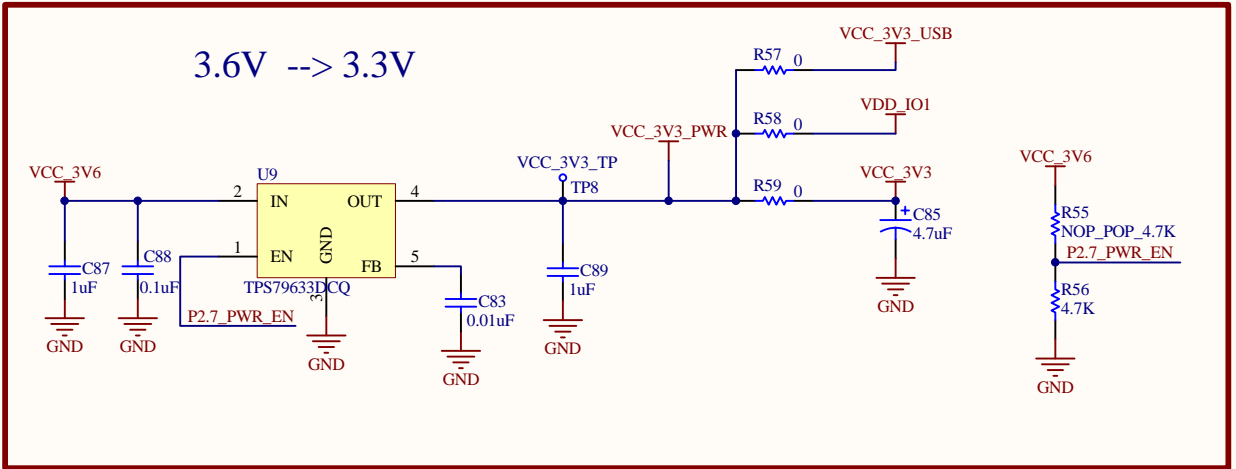
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2		revised by:	Date:
3		revised by:	Date:





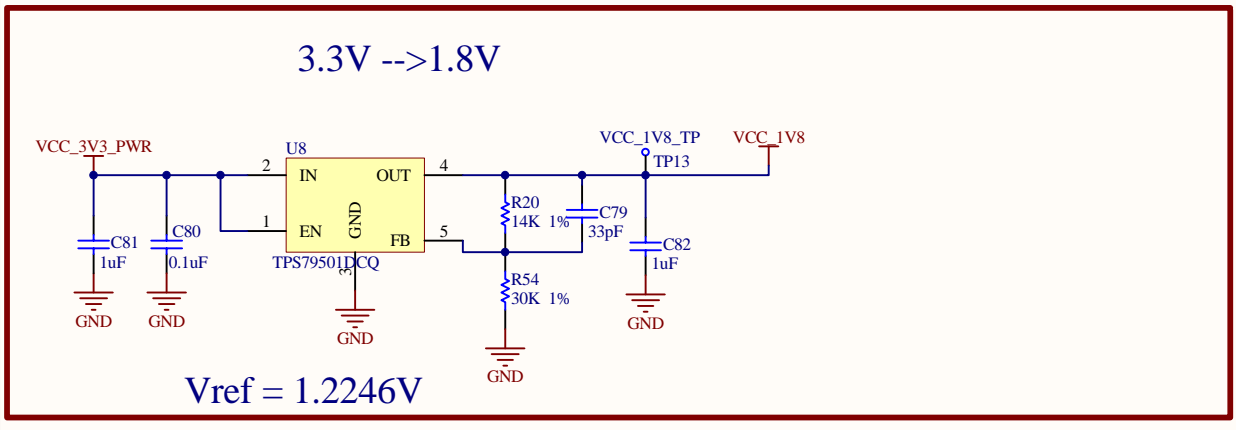
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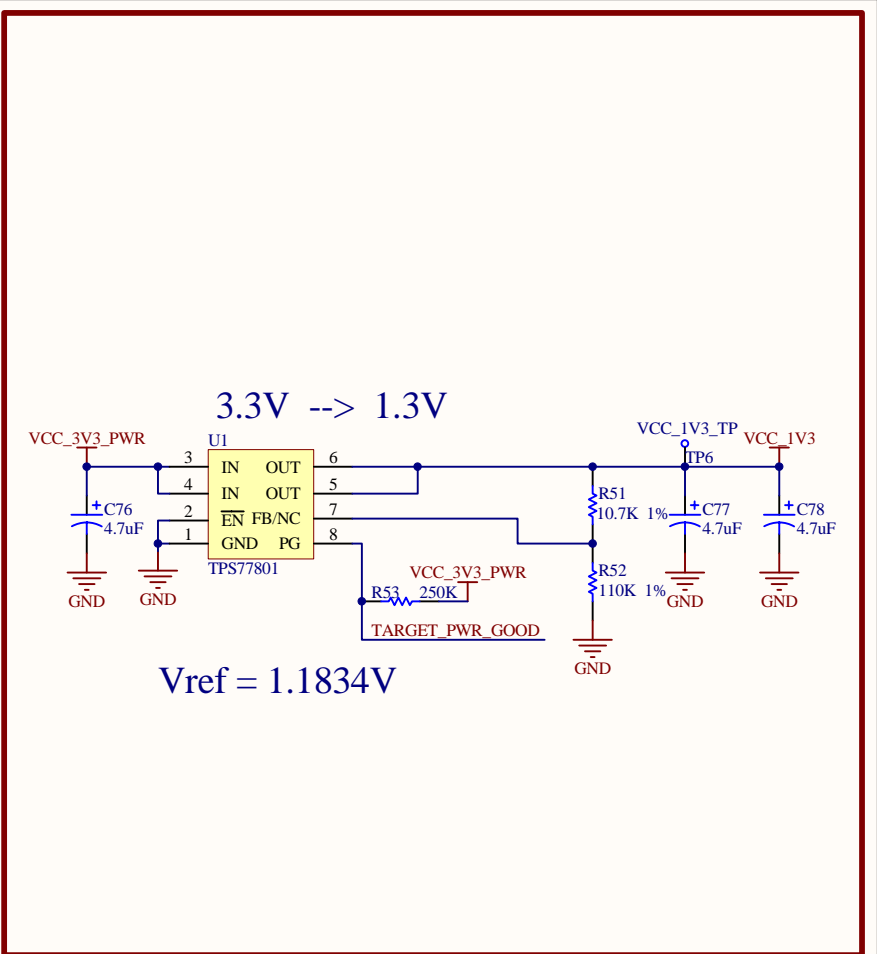
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B



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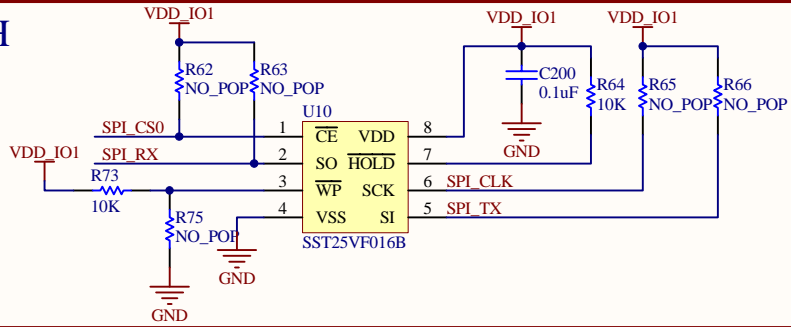
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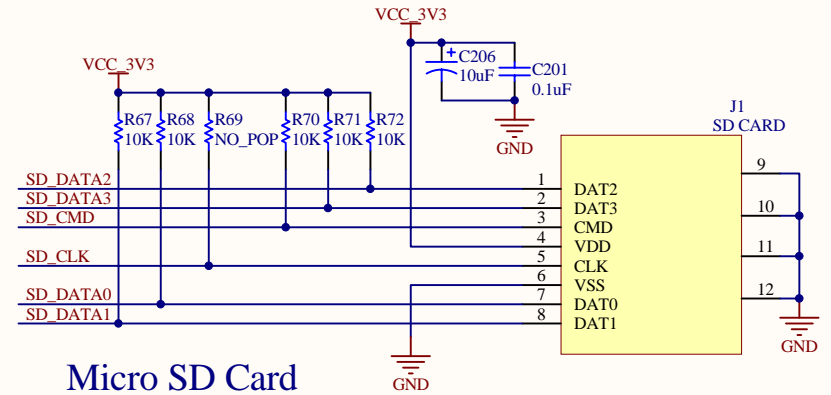
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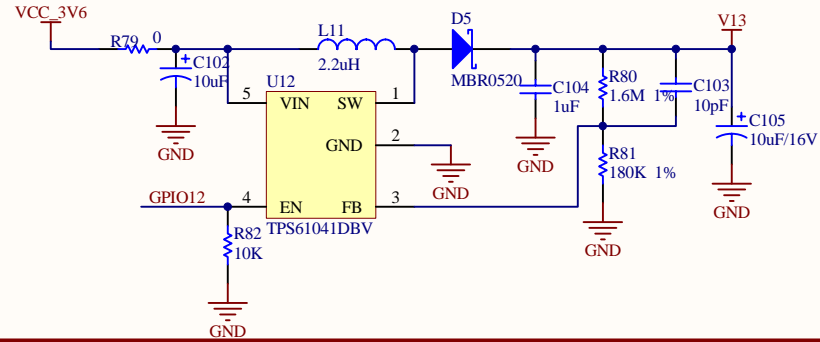
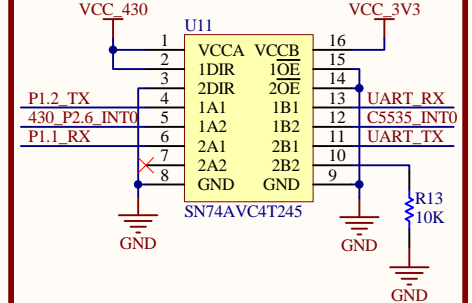
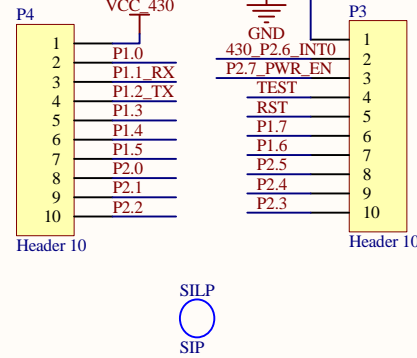
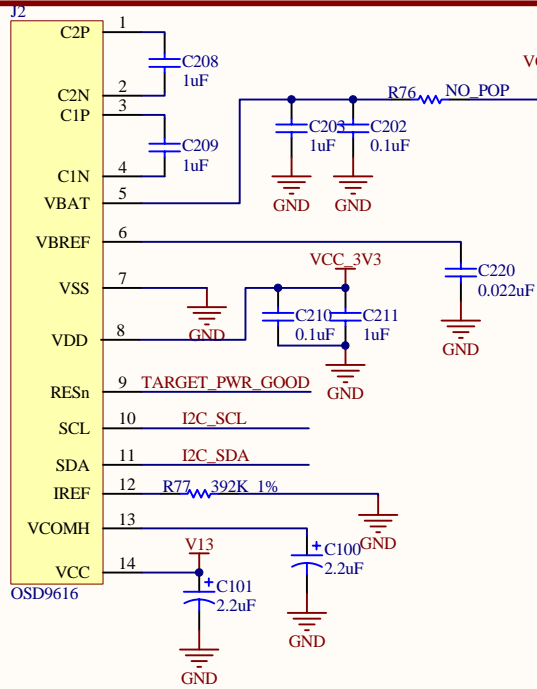
SPI FLASH



Micro SD Card

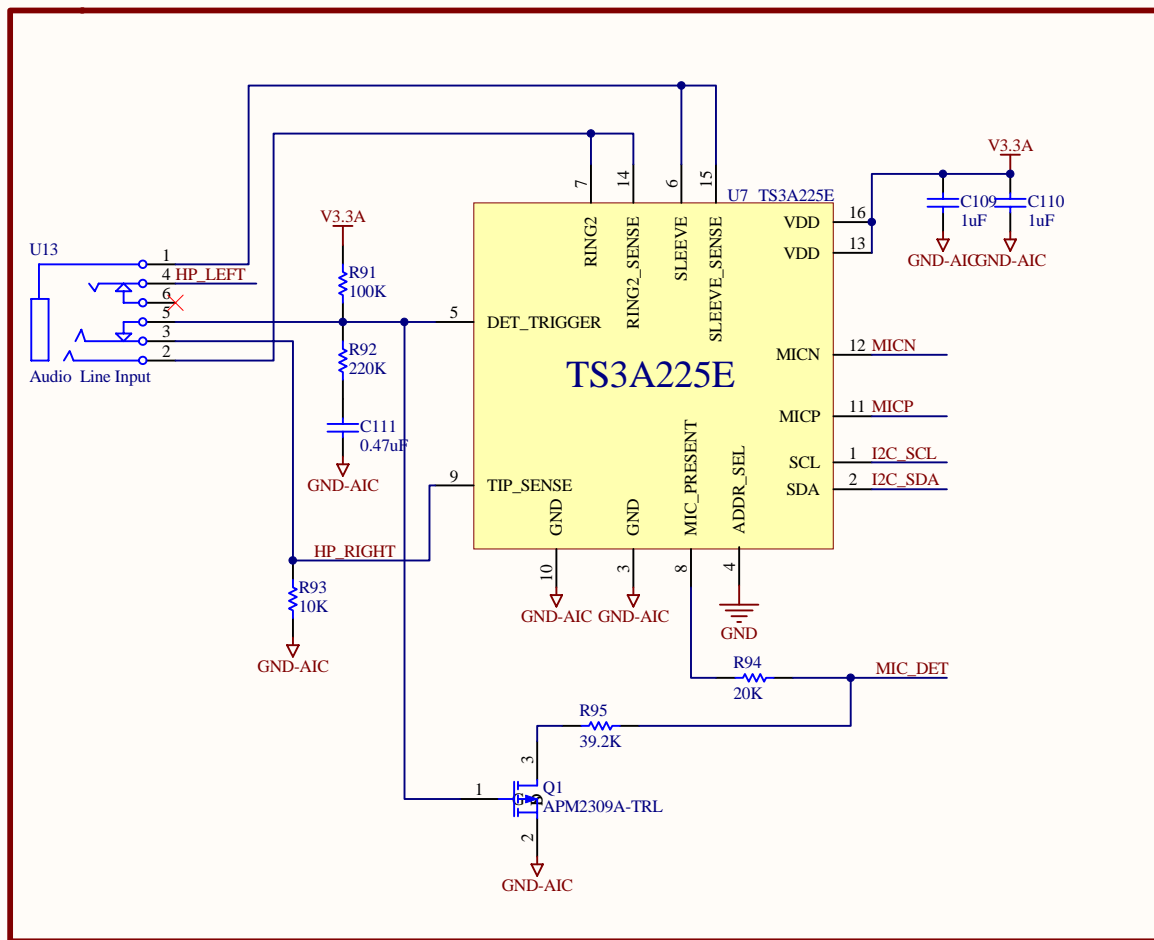


OLED



Project Name: Audio Capacitive Touch Booster Pack		Project No.: 430BOOST-C55AUDIO1	
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3		revised by:	Date:





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